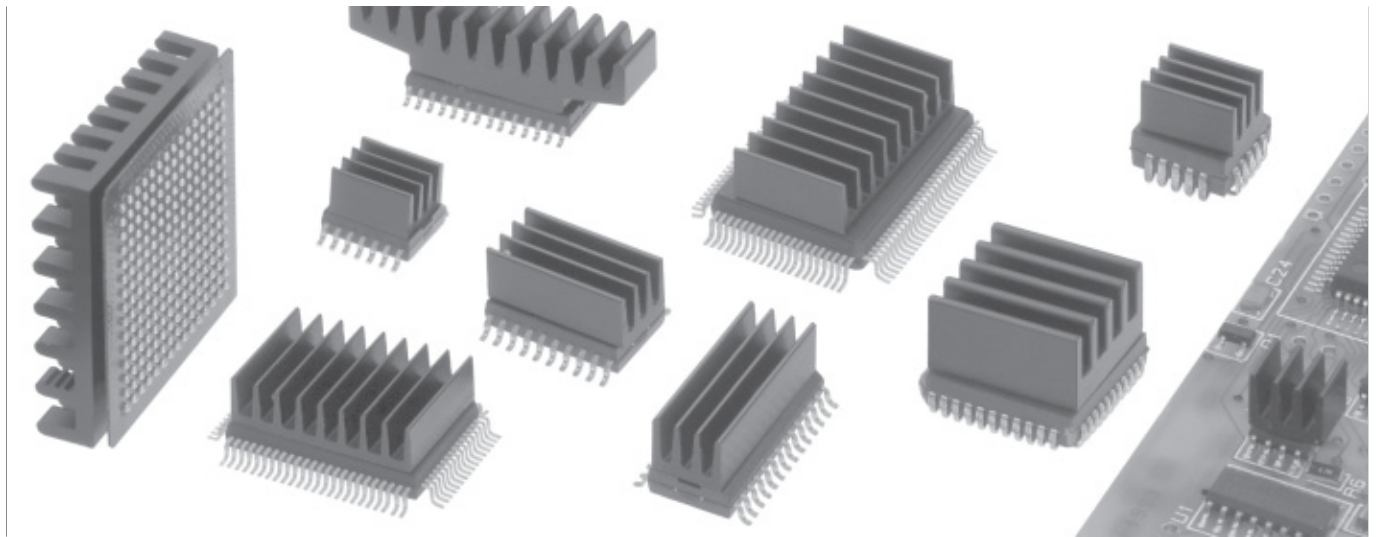
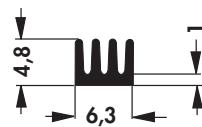


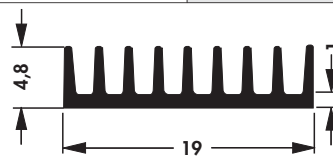
Heatsinks for SMD



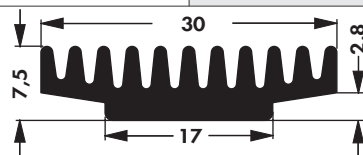
- particularly suitable for SMD components
- low profile
- reduced weight
- effective heat dissipation
- can be glued directly onto the component
- solderable versions
- customer specific versions on request
- special packaging like tape and reel, bar magazine, tray etc. on request



art. no.	width [mm]	R_{th} [K/W]	art. no.	width [mm]	R_{th} [K/W]
ICK SMD A 5 ...	5	123	ICK SMD A 13 ...	13	63
ICK SMD A 8 ...	8	87	ICK SMD A 17 ...	17	51
ICK SMD A 10 ...	10	75	ICK SMD A 22 ...	22	34



art. no.	width [mm]	R_{th} [K/W]	art. no.	width [mm]	R_{th} [K/W]
ICK SMD B 5 ...	5	56	ICK SMD B 13 SA	13	29
ICK SMD B 7 SA	7	47	ICK SMD B 19 ...	19	22
ICK SMD B 10 SA	10	35			



art. no.	width [mm]	R_{th} [K/W]	art. no.	width [mm]	R_{th} [K/W]
ICK SMD C 7 SA	7	33	ICK SMD C 17 ...	17	17
ICK SMD C 10 SA	10	26			

please indicate: ... surface
SA = black anodised
MI = solderable surface

B 45

Extruded heatsinks
 Pin heatsinks for IC
 Insulating clamping parts
 Thermal conductive glue

→ A 22 - 83
 → B 21 - 27
 → E 43
 → E 21 - 22

Thermally conductive foil
 Thermal conductive paste
 Hole pattern
 Technical introduction

→ E 5 - 13
 → E 19 - 20
 → A 21
 → A 2 - 7